



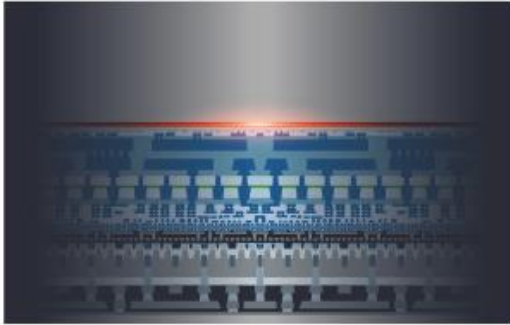
Member of the Week – March 17, 2023



## Will the Green Shoots Be Damaged by a Long Winter?

“Green shoots” refers to signs of economic recovery. As a former analyst, I always found forecasting for the next year in December to be the biggest challenge, and perhaps the biggest miss of the year. You essentially are working without a net. Historically calendar Q4 revenue estimates by the equipment companies are positive, as the semiconductor manufacturers are spending the last of their budgets.

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## Member of the Week



EV Group (EVG) is a leading supplier of equipment and process solutions for the manufacture of semiconductors, microelectromechanical systems (MEMS), compound semiconductors, power devices, and nanotechnology devices. Key products include wafer bonding, thin-wafer processing, lithography/nanoimprint lithography (NIL) and metrology equipment, as well as photoresist coaters, cleaners, and inspection systems. [Congratulations](#) to EVG for being named this year's 3D InCites recipient of Process of the Year for its NanoCleave, a revolutionary layer release technology for silicon that enables ultra-thin layer stacking for front-end processing, including advanced logic, memory, and power device formation, as well as advanced packaging. It is a fully front-end-compatible layer release technology featuring an IR laser that can pass through silicon. Coupled with the use of specially formulated inorganic layers, this technology enables an IR laser-initiated release of any ultra-thin film or layer from silicon carriers with nanometer precision. NanoCleave enables silicon wafer carriers in advanced packaging processes such as FOWLIP using mold/reconstituted wafers and interposers for 3D-SICs.

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### Company News

[MKS Instruments Introduces Industry Leading Integrated Approach to Creating Solutions for Complex Package Substrate Manufacturing Requirements and Roadmaps](#)

[Lam Research Named as One of Ethisphere's 2023 World's Most Ethical Companies](#)

[IMAPS Advanced System-in-Package Conference is now CHIPcon](#)

### Recommended Reads

[Panel Tackles Chiplet Packaging Challenges – SemiEngineering](#)

[Tech Forecast: Fab Processes To Watch Through 2040 – SemiEngineering](#)

### Events Calendar

[CALL FOR PAPERS: DATE 2023 Workshop on "3D Integration: Heterogeneous 3D Architectures and Sensors"](#)

April 17-19

[34th Annual Advanced Semiconductor Manufacturing Conference](#)

May 1, 2023

[ECTC 2023](#)

May 30-June 1, 2023



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